

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.87481	100.0	12.7
			Subtotal	0.87481	100	12.7
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.44085	100.0	6.4
	Pure metal	Aluminium (Al)	7429-90-5	0.01027	100.0	0.1491
			Subtotal	0.45112	200	6.5491
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.72206	100.0	25
			Subtotal	1.72206	100	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02314	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05786	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	57.78023	99.86	838.824
			Subtotal	57.86123	100	840
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.37093	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.19942	16.0	90
	Filler	Silica fused	60676-86-0	29.05977	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11624	0.3	1.6875
			Subtotal	38.74636	100	562.5
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01722	5.0	0.25
	Lead alloy	Silver (Ag)	7440-22-4	0.00861	2.5	0.125
	Lead alloy	Lead (Pb)	7439-92-1	0.31858	92.5	4.625
			Subtotal	0.34441	100	5
			Total	99.99999	100	1451.7491

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